

ABSTRACT

Disclosed are an electroplating device and a cleaning method. The electroplating device comprises a process chamber, configured to store an electroplating solution; a substrate holder, including a holder main body and a sealing member; a driving system, configured to drive the substrate holder to ascend, lower, and rotate; a cleaning system, including a nozzle, a cleaning liquid tank, and a cleaning liquid supply pipe, wherein the nozzle is provided with an obliquely upward spraying direction, so as to spray a cleaning liquid to a preset position of a substrate and/or the sealing member for cleaning the sealing member, and the spraying direction has a component aligned with the tangential direction of the rotation direction of the substrate holder at the preset position; and a control system, configured to control the driving system to lift or lower the substrate holder to a preset height above the nozzle and rotate the substrate holder at a preset rotating speed during the cleaning of the sealing member, and control the cleaning system to enable the nozzle to spray the cleaning liquid at a preset flow rate. The present application achieves the cleaning function for the sealing member and reduces the dripping amount of cleaning liquid during the cleaning of the sealing member.